
New Sub-pixel Structured OLED Microdisplay

Rigo Herold

Fraunhofer Research Institution for Organics, Materials and Electronic Devices COMEDD, Branch Center for Organic Materials and Electronic Devices Dresden (COMEDD), Dresden, Germany

Dr. Rigo Herold

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Outline

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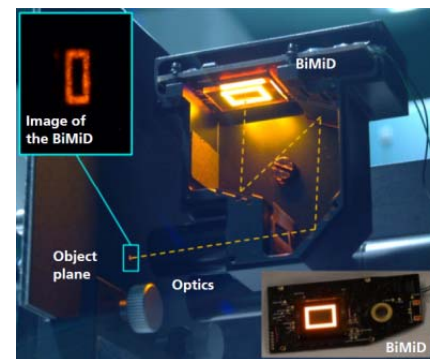
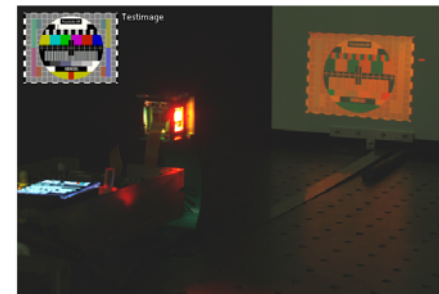
1. Motivation

■ Microdisplay Applications

- Data glasses
- Pico projectors
- Head-up displays
- Sensors

■ Microdisplay demands

- Coloured
- High brightness $> 10.000 \text{ cd/m}^2$
- Low Power
- High resolution
- Small dimensions
- Low priced manufacturing



1. Motivation

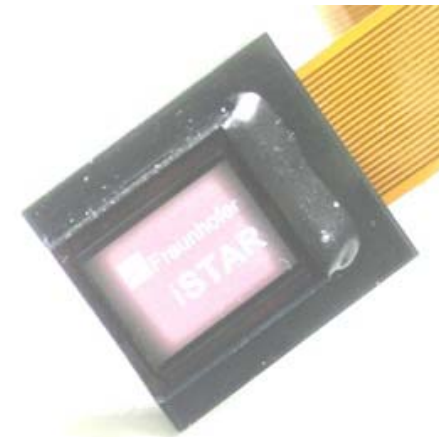
■ Coloured vs. Brightness dilemma

■ State-of-the-art

- White OLED matrix + colour filter (CF)
- 2/3% loss of luminance by colour filtering
- Colour filter transmission losses
 - Up to 80% reduction of brightness

■ Possible solution

- Sub-pixel structuring of red, green & blue emitters
 - Reduction of colour filter losses
 - Use of efficient OLED stacks for each colour



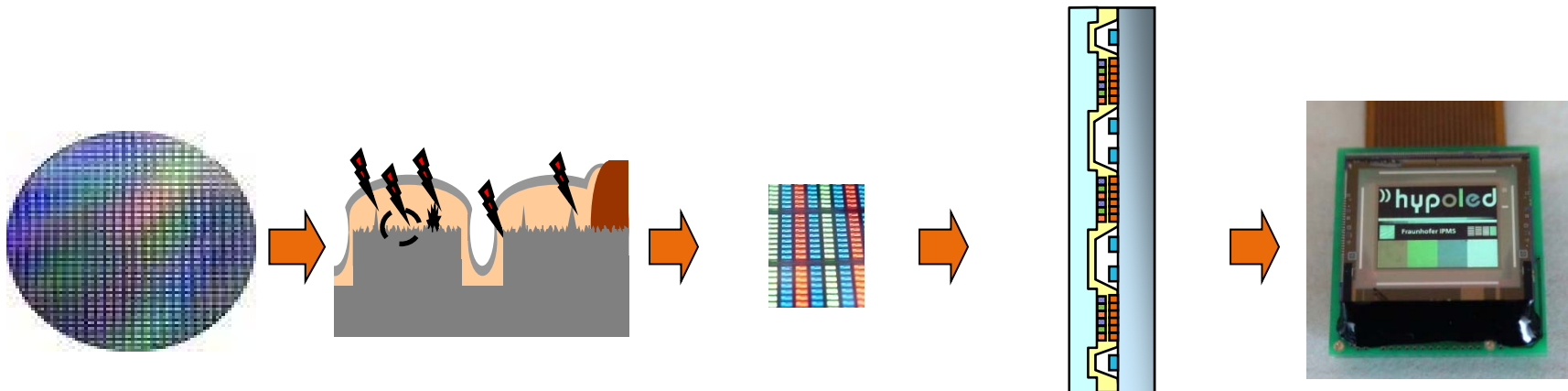
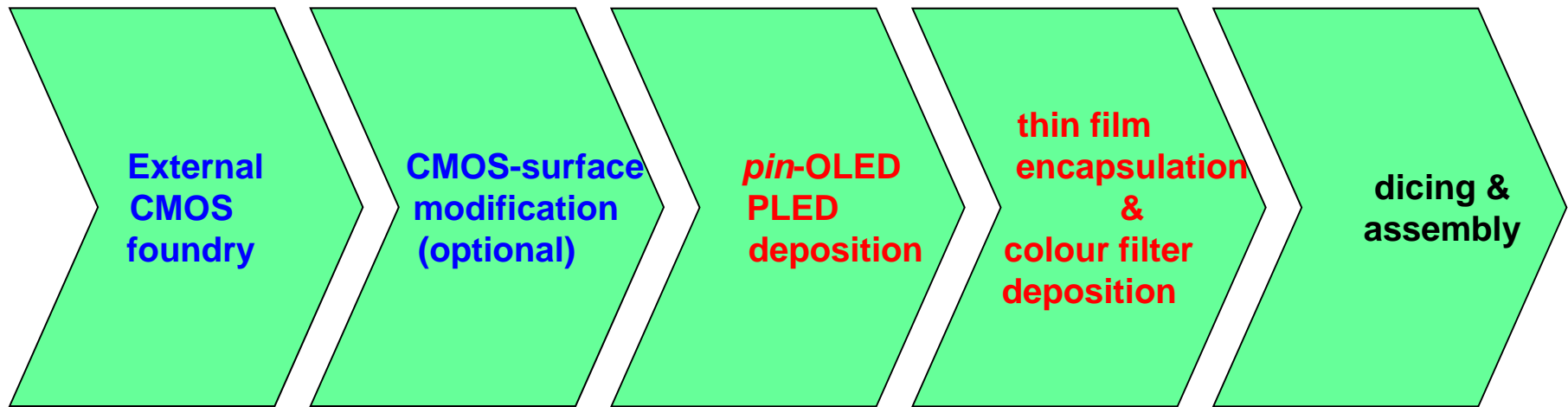
Microdisplay without CF



Microdisplay with CF

2. Sub-pixel structuring process

- Standard OLED-on-Silicon process flow



2. Sub-pixel structuring process

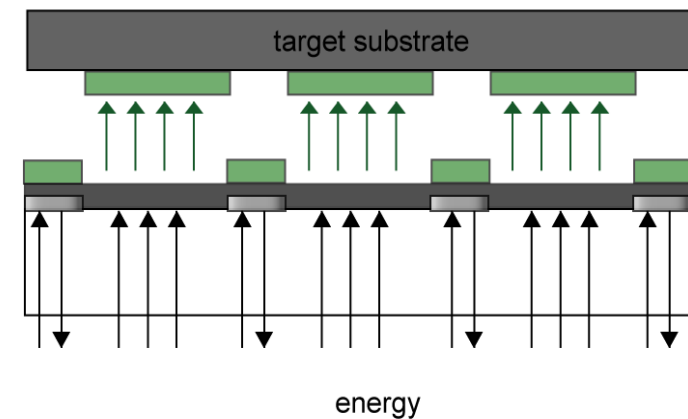
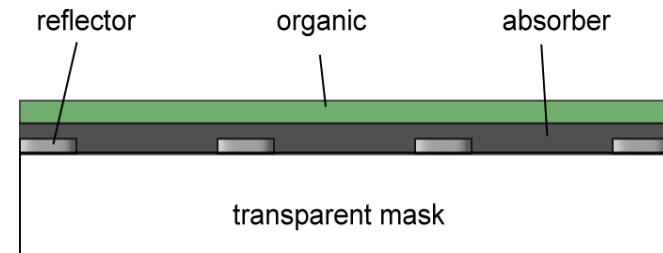
■ Flash-Mask-Transfer-Lithography

■ Transfer mask

- Donor substrate
- Patterned reflectors and absorbers
- Absorber define the pixel geometry
- Organic emitter is deposited on the top

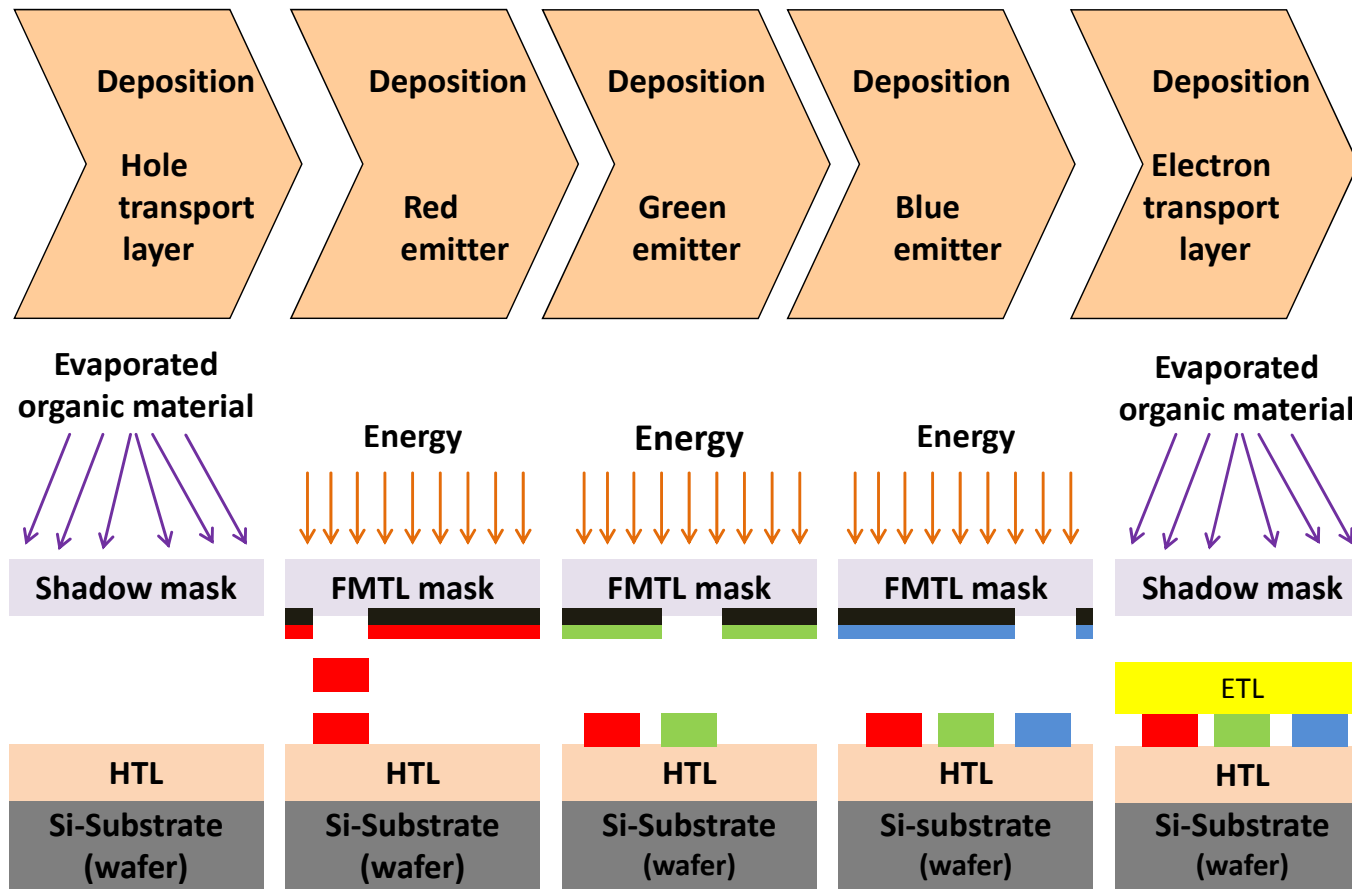
■ Transfer process

- Target aligned to the FMTL mask
- Energy on the mask bottom
- Material above the absorber is evaporated and transferred to the target



2. Sub-pixel structuring process

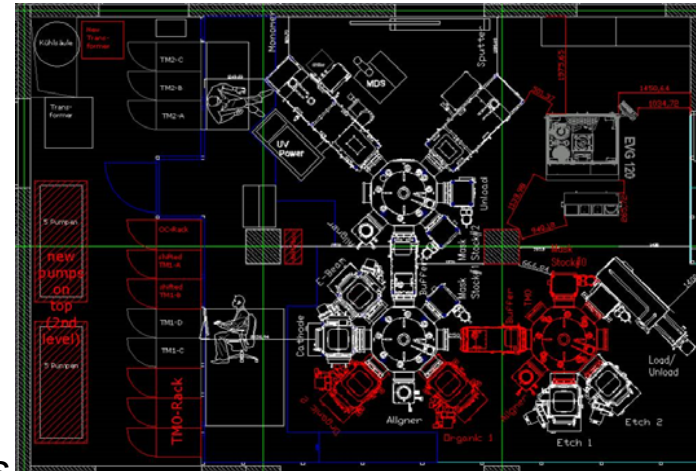
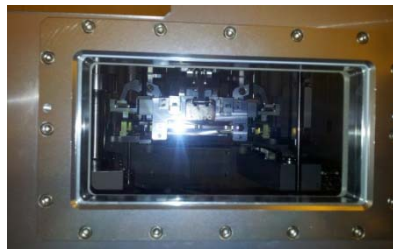
- Manufacturing steps of color sub-pixel structured OLED microdisplays



2. Sub-pixel structuring process

■ OLED-Microdisplay Cleanroom

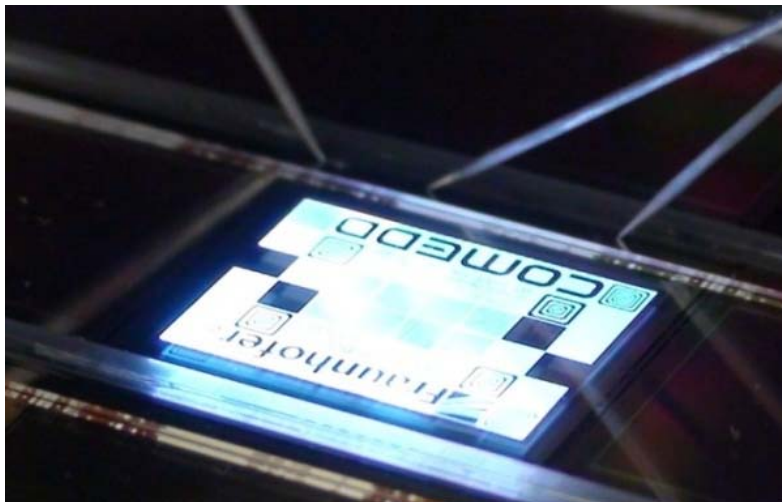
- 300 m² clean room class 10
- Etching / Sputtering Clustex 200 | Leybold Optics
- Spin coating EVG120 | EVG
- Etching, deposition by thermal evaporation, ebeam and Barix™ thinfilm encapsulation
- Full-automated wafer bonding system Hercules | EVG
- Photolithography (Nanoimprint). EVG IQ + Brewer automatic processing station.
- Wafer prober Pegasus PA200 | Wentworth



3. Demonstrators at the exhibition

- Test Display for FMTL process evaluation
 - Designed for 180nm CMOS-process
 - Test structures down to $8\mu\text{m} \times 8\mu\text{m}$
 - Evaluated with a standard OLED deposition

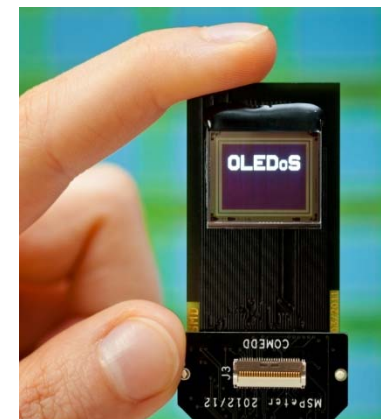
Wafer test



Layout



Exhibited demo

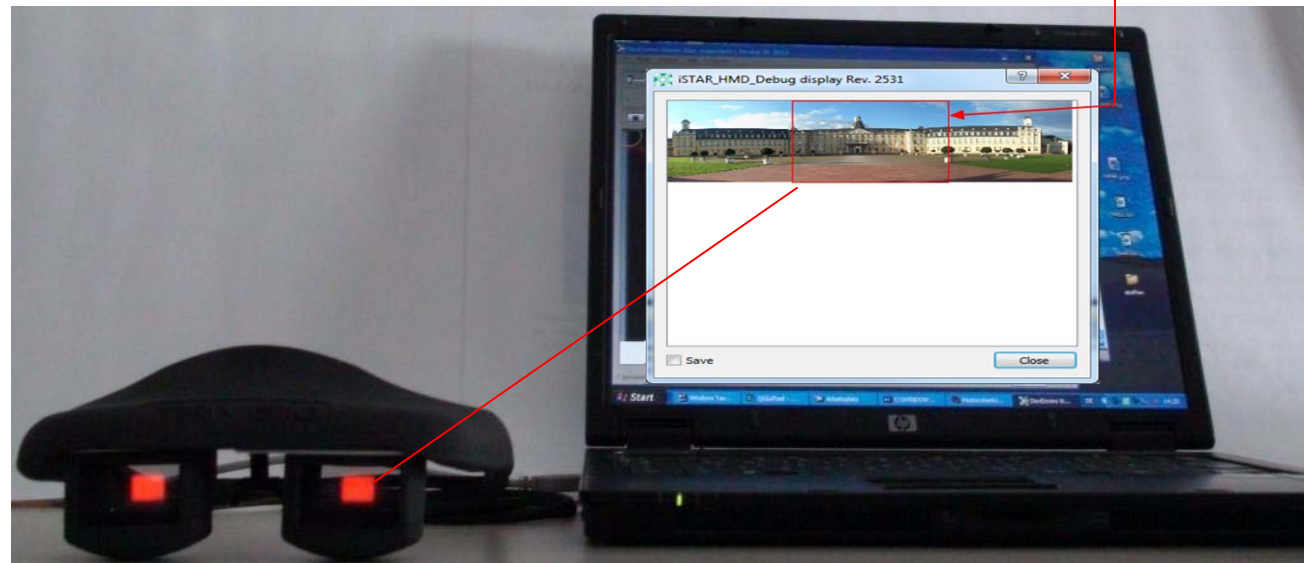


3. Demonstrators at the exhibition

- Interactive Data glasses
 - Panorama view „Castle of Karlsruhe“
 - Moved by the users eye

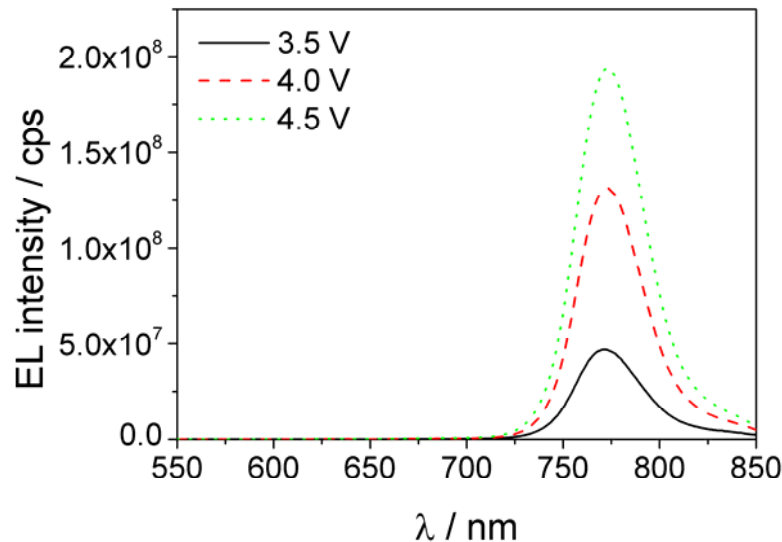


Gaze triggered
Point of view



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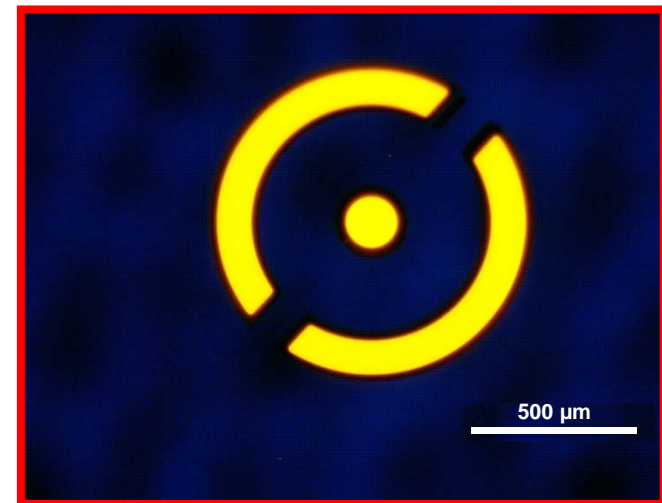
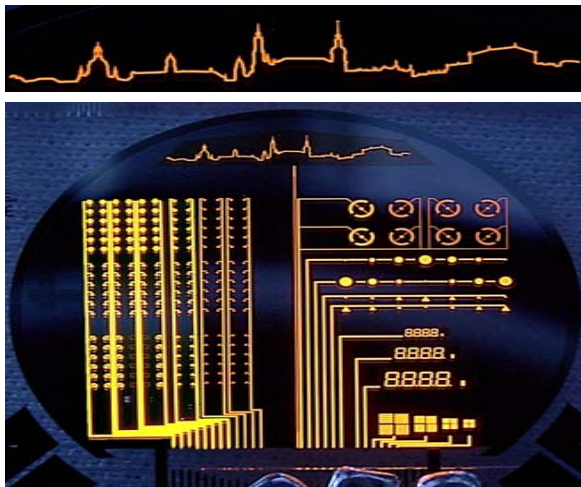
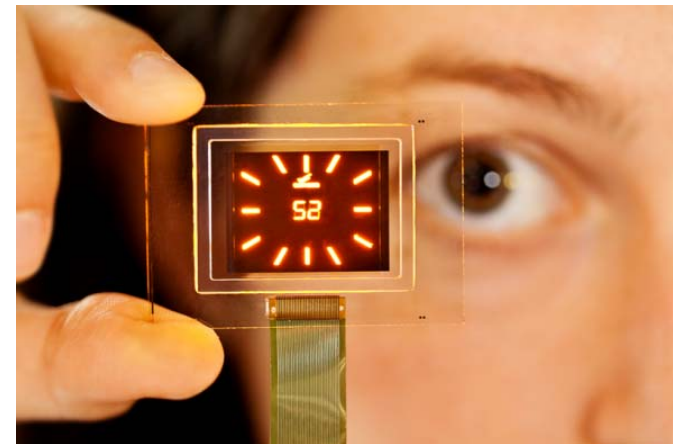
- NIR active OLEDs and their integration in CMOS Microdisplays
 - Co-integration with OLED emitters in the visible area
 - Integration on transparent and flexible substrates also possible



3. Demonstrators at the exhibition

■ OPTICAL MICROSTRUCTURES WITH OLED

- Top and bottom emitting OLEDs
- OLED structures on transparent glas
- Smallest feature size 5µm
- Local control electronic
- Customized layouts possible



4. Outlook and Acknowledgement

■ Outlook

- First true RGB OLEDs on microdisplays
- Manufacturing process optimization

■ Acknowledgement

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■ Speaker contact

- Dr. Rigo Herold
- @SID'13 : booth 1209
- Email: rigo.herold@comedd.fraunhofer.de
- phone:+49-351-8823-216

**Thank you for
attention**